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## Product Change Notification - JAON-13SZRI638 [\(Printer Friendly\)](#)

**Date:** 09 Oct 2016

**Product Category:** Memory; Analog (Linear & Mixed Signal) AND Interface; Analog (Thermal, Power Management & Safety)

**Notification subject:** CCB 1545 Final Notice: Qualification of CuPdAu bond wire, 8600 die attach and G700LTD mold compound material in selected products of the 160K wafer technology available in 8L TDFN package at NSEB site

**Notification text:** **PCN Status:**  
Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material in selected products of the 160K wafer technology available in 8L TDFN package at NSEB assembly site.

**Pre Change:**

Using gold (Au) bond wire, 8200T die attach and G770HCD mold compound material.

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	NSEB assembly site	NSEB assembly site

<b>Wire material</b>	Au wire	CuPdAu wire
<b>Die attach material</b>	8200T	8600
<b>Molding compound material</b>	G770HCD	G700LTD
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability and qualify CuPdAu bond wire, 8600 die attach and G700LTD mold compound material at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

November 25, 2016 (date code: 1647)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	April 2015				->	October 2016				November 2016			
	14	15	16	17		40	41	42	43	44	45	46	47
Workweek													
Initial PCN Issue Date			X										
Qual Report Availability													
Final PCN Issue Date						X							
Estimated Implementation													





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